MMBT2907AL, SMMBT2907AL

General Purpose Transistors

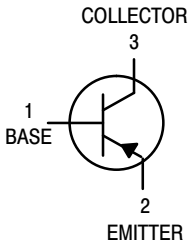
PNP Silicon

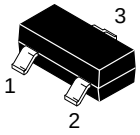
ON Semiconductor®

www.onsemi.com

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant





SOT−23 (TO−236AB)
CASE 318
STYLE 6

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector−Emitter Voltage	V_{CEO}	−60	Vdc
Collector−Base Voltage	V_{CBO}	−60	Vdc
Emitter−Base Voltage	V_{EBO}	−5.0	Vdc
Collector Current − Continuous	I_C	−600	mAdc
Collector Current − Peak (Note 3)	I_{CM}	−1200	mAdc

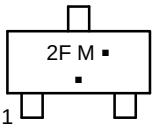
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation − FR−5 Board (Note 1) @T_A = 25°C Derate above 25°C	P_D	225 1.8	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation − Alumina Substrate, (Note 2) @T_A = 25°C Derate above 25°C	P_D	300 2.4	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	417	°C/W
Total Device Dissipation − Heat Spreader or equivalent, (Note 4) @T_A = 25°C	P_D	350	mW
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	357	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR−5 = 1.0 × 0.75 × 0.062 in.
2. Alumina = 0.4 × 0.3 × 0.024 in. 99.5% alumina.
3. Reference SOA curve.
4. Heat Spreader or equivalent = 450 mm^2, 2 oz.

MARKING DIAGRAM



2F = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMBT2907ALT1G SMMBT2907ALT1G	SOT−23 (Pb−Free)	3000 / Tape & Reel
MMBT2907ALT3G SMMBT2907ALT3G	SOT−23 (Pb−Free)	10,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector−Emitter Breakdown Voltage (Note 5) (I_C = −1.0 mAdc, I_B = 0) (I_C = −10 mAdc, I_B = 0)	$V_{(BR)CEO}$	 −60 −60	 − −	Vdc
Collector−Base Breakdown Voltage (I_C = −10 μAdc, I_E = 0)	$V_{(BR)CBO}$	−60	−	Vdc
Emitter−Base Breakdown Voltage (I_E = −10 μAdc, I_C = 0)	$V_{(BR)EBO}$	−5.0	−	Vdc
Collector Cutoff Current (V_{CE} = −30 Vdc, $V_{EB(off)}$ = −0.5 Vdc)	I_{CEX}	−	−50	nAdc
Collector Cutoff Current (V_{CB} = −50 Vdc, I_E = 0) (V_{CB} = −50 Vdc, I_E = 0, T_A = 125°C)	I_{CBO}	 − −	 −0.010 −10	μAdc
Base Cutoff Current (V_{CE} = −30 Vdc, $V_{EB(off)}$ = −0.5 Vdc)	I_{BL}	−	−50	nAdc
ON CHARACTERISTICS				
DC Current Gain (I_C = −0.1 mAdc, V_{CE} = −10 Vdc) (I_C = −1.0 mAdc, V_{CE} = −10 Vdc) (I_C = −10 mAdc, V_{CE} = −10 Vdc) (I_C = −150 mAdc, V_{CE} = −10 Vdc) (I_C = −500 mAdc, V_{CE} = −10 Vdc) (Note 5)	h_{FE}	 75 100 100 100 50	 − − − 300 −	−
Collector−Emitter Saturation Voltage (Note 5) (I_C = −150 mAdc, I_B = −15 mAdc) (Note 5) (I_C = −500 mAdc, I_B = −50 mAdc)	$V_{CE(sat)}$	 − −	 −0.4 −1.6	Vdc
Base−Emitter Saturation Voltage (Note 5) (I_C = −150 mAdc, I_B = −15 mAdc) (I_C = −500 mAdc, I_B = −50 mAdc)	$V_{BE(sat)}$	 − −	 −1.3 −2.6	Vdc
SMALL−SIGNAL CHARACTERISTICS				
Current−Gain − Bandwidth Product (Notes 5, 6), (I_C = −50 mAdc, V_{CE} = −20 Vdc, f = 100 MHz)	f_T	200	−	MHz
Output Capacitance (V_{CB} = −10 Vdc, I_E = 0, f = 1.0 MHz)	C_{obo}	−	8.0	pF
Input Capacitance (V_{EB} = −2.0 Vdc, I_C = 0, f = 1.0 MHz)	C_{ibo}	−	30	
SWITCHING CHARACTERISTICS				
Turn−On Time	(V_{CC} = −30 Vdc, I_C = −150 mAdc, I_{B1} = −15 mAdc)	t_{on}	−	45	ns
Delay Time		t_d	−	10	
Rise Time		t_r	−	40	
Turn−Off Time	(V_{CC} = −6.0 Vdc, I_C = −150 mAdc, I_{B1} = I_{B2} = −15 mAdc)	t_{off}	−	100	
Storage Time		t_s	−	80	
Fall Time		t_f	−	30	

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
6. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.

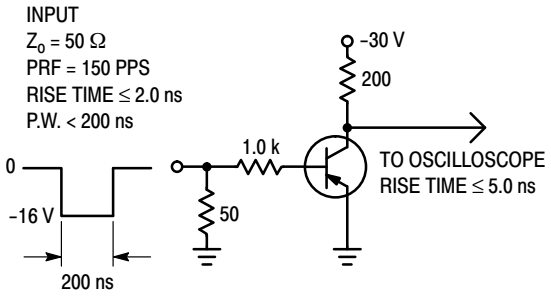


Figure 1. Delay and Rise Time Test Circuit

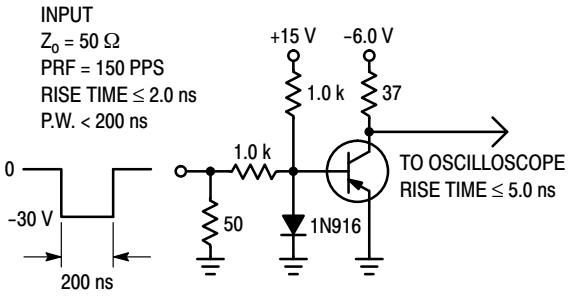


Figure 2. Storage and Fall Time Test Circuit

TYPICAL CHARACTERISTICS

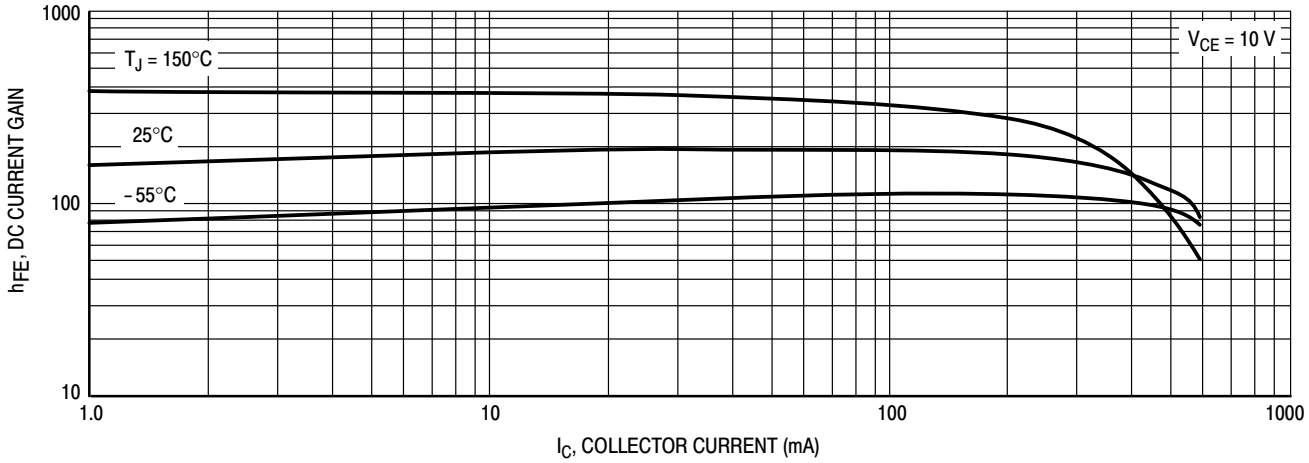


Figure 3. DC Current Gain

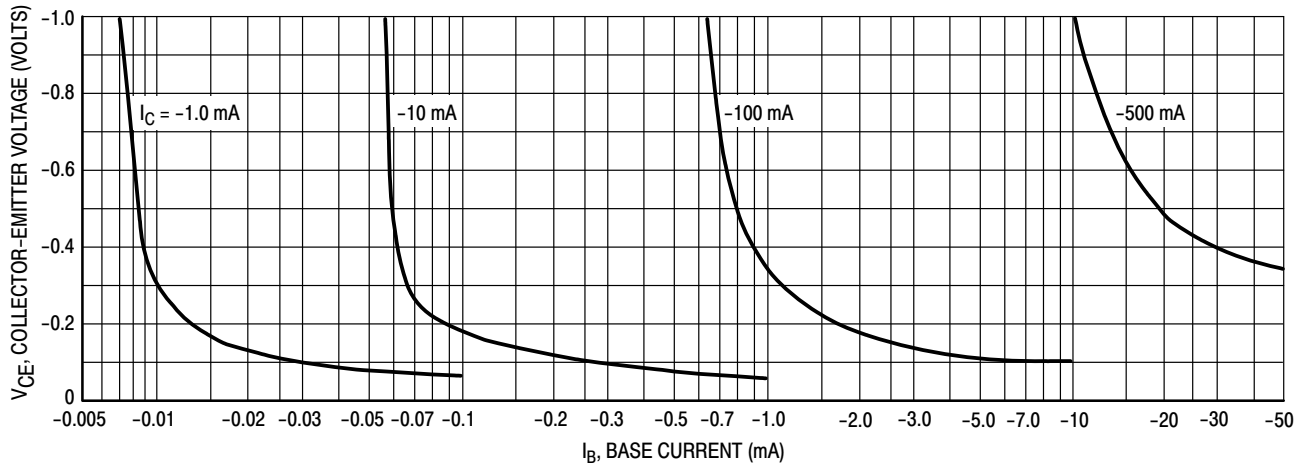


Figure 4. Collector Saturation Region

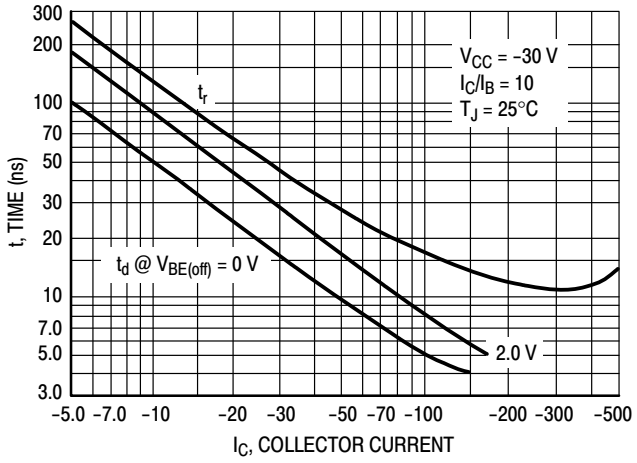


Figure 5. Turn−On Time

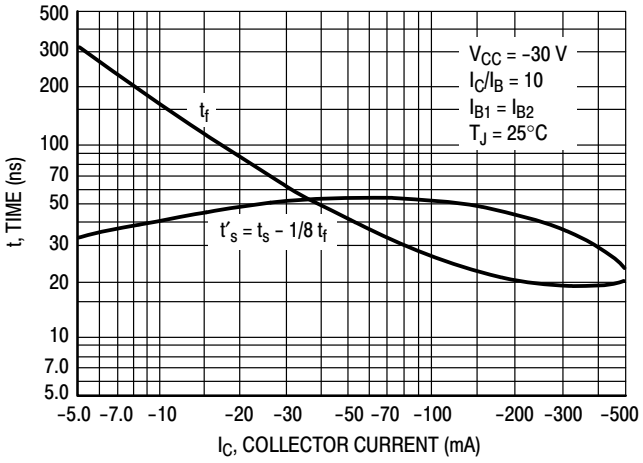


Figure 6. Turn−Off Time

TYPICAL SMALL−SIGNAL Characteristics

NOISE FIGURE

V_{CE} = 10 Vdc, T_A = 25°C

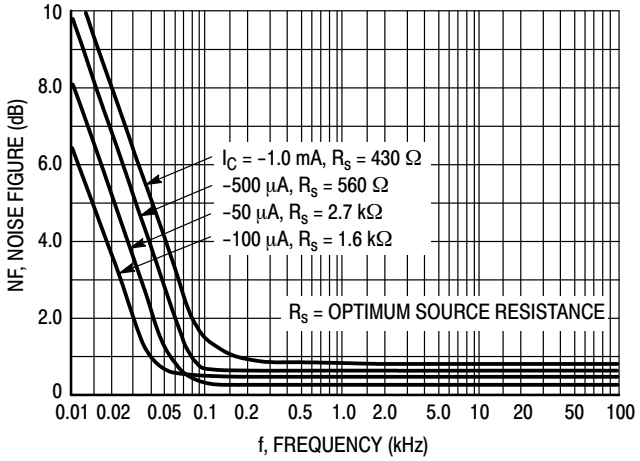


Figure 7. Frequency Effects

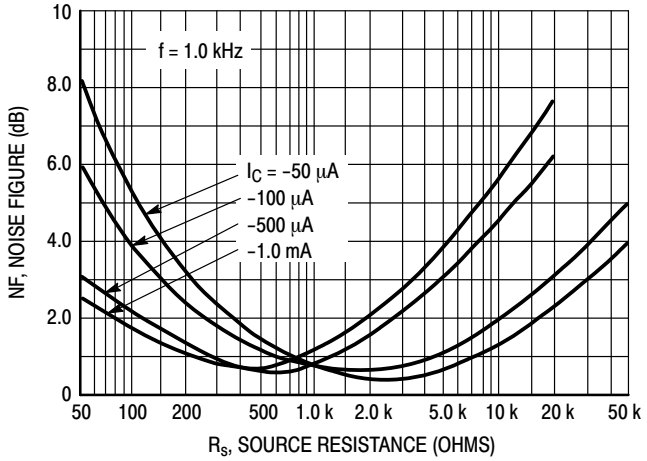


Figure 8. Source Resistance Effects

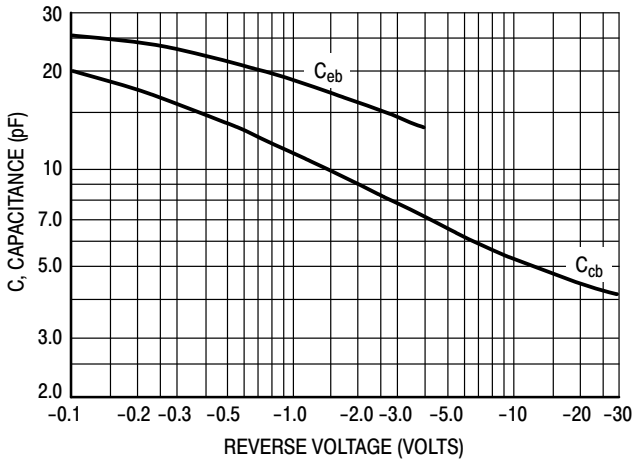


Figure 9. Capacitances

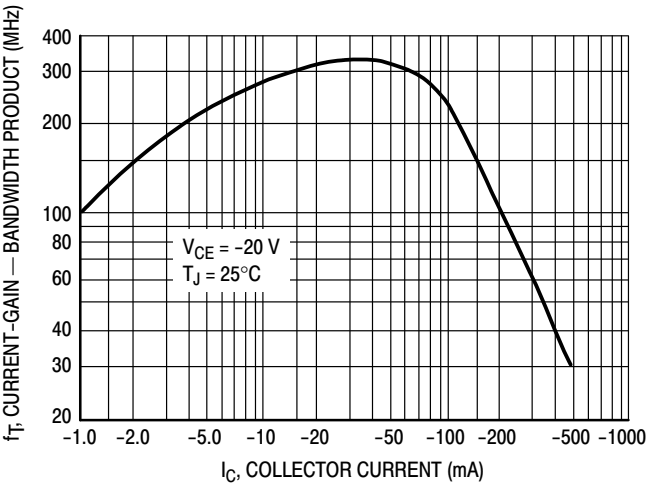


Figure 10. Current−Gain − Bandwidth Product

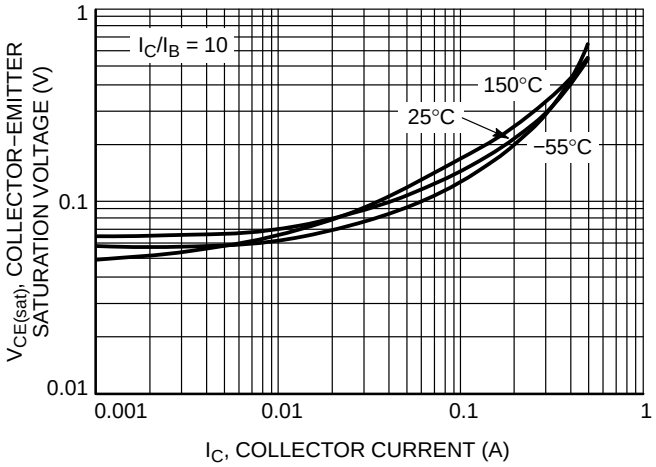


Figure 11. Collector Emitter Saturation Voltage vs. Collector Current

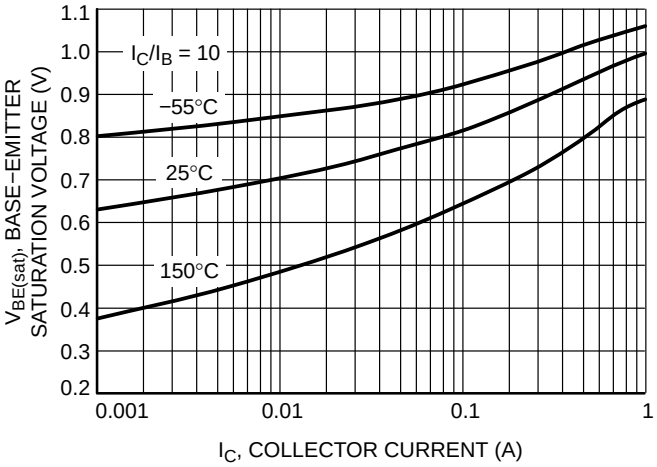


Figure 12. Base Emitter Saturation Voltage vs. Collector Current

TYPICAL SMALL−SIGNAL Characteristics

NOISE FIGURE

V_{CE} = 10 Vdc, T_A = 25°C

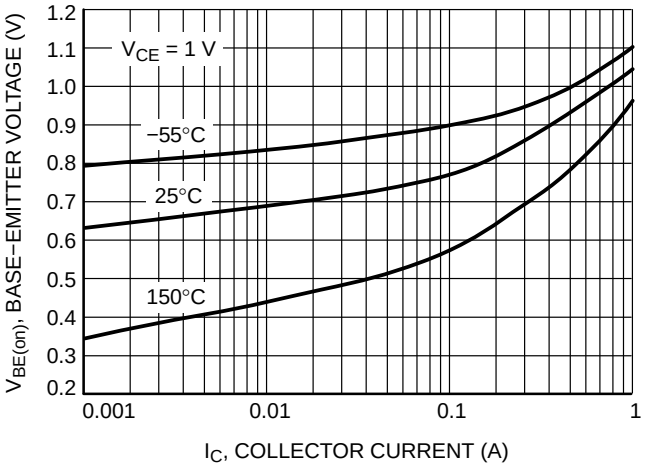


Figure 13. Base Emitter Voltage vs. Collector Current

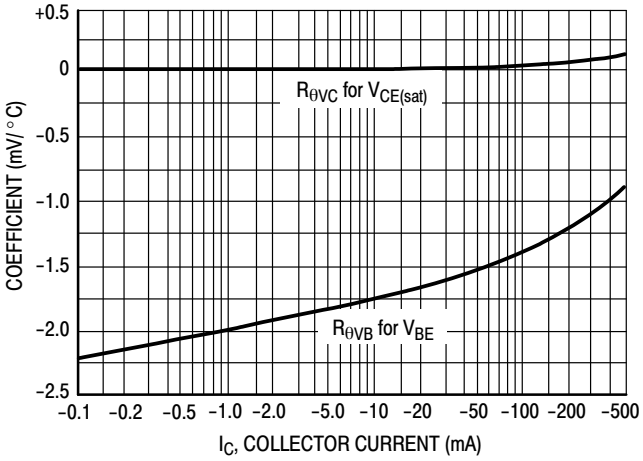


Figure 14. Temperature Coefficients

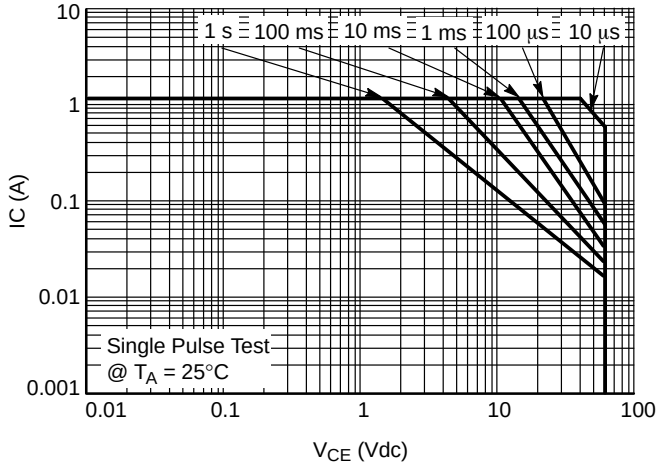
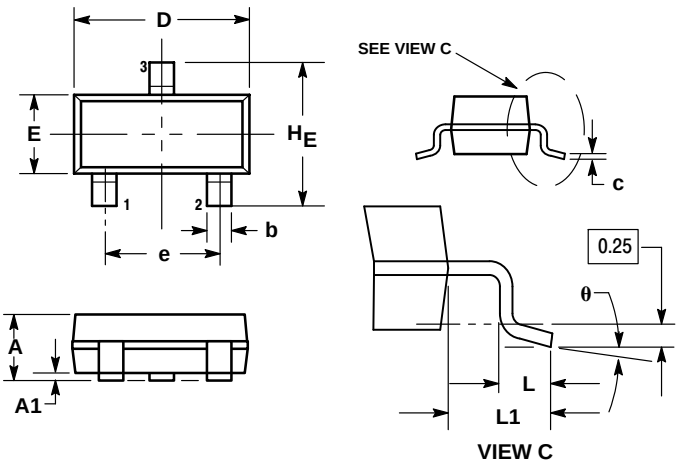


Figure 15. Safe Operating Area

PACKAGE DIMENSIONS

SOT−23 (TO−236)
CASE 318−08
ISSUE AP

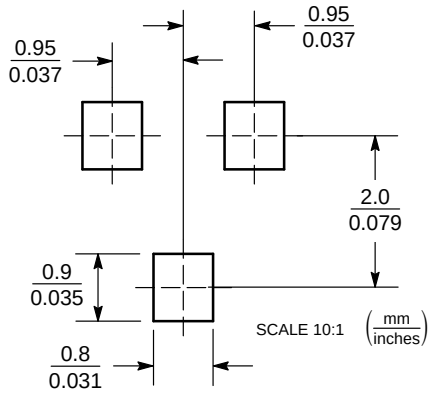


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H_E	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	−−−	10°	0°	−−−	10°

STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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